

Application Serial No: 10/580,157

Responsive to the Office Action mailed on: November 27, 2007

### **IN THE CLAIMS**

#### **Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

1. (Currently Amended) A circuit board comprising:  
an insulating base board;  
a conductive pad provided on the base board; and  
a metal member bonded to the pad via a solder layer, the metal member including a welding portion ~~to which a weldable object is welded; and~~  
a terminal welded to the welding portion of the metal member;  
wherein an air gap exists between the welding portion of the metal member and the base board, the welding portion and the solder layer being spaced from each other via the air gap.
2. (Original) The circuit board according to claim 1, wherein the metal member is formed with a recess which serves as at least a part of the air gap.
3. (Original) The circuit board according to claim 1, wherein the metal member includes two ends folded in a common direction, the ends outlining a space which serves as at least a part of the air gap.
4. (Original) The circuit board according to claim 2, wherein the metal member includes two ends and a central portion which is positioned higher than the ends, the two ends outlining a space which serves as the recess.
5. (Original) The circuit board according to claim 2, wherein the recess is formed by etching the metal member.

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6. (Original) The circuit board according to claim 1, wherein the metal member is a flat pipe having a hollow portion, the hollow portion serving as the air gap.

7. (Original) The circuit board according to claim 1, wherein the solder layer is divided into a plurality of areas spaced from each other, the plurality of solder areas outlining a space which serves as at least a part of the air gap.

8. (Original) The circuit board according to claim 7, wherein the pad is divided into a plurality of parts each corresponding to respective one of the plurality of solder areas.